

SOT109-1

plastic small outline package; 16 leads; body width 3.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO16
Package type industry code	SO16
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	076E07
JEDEC package outline code	MS-012
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

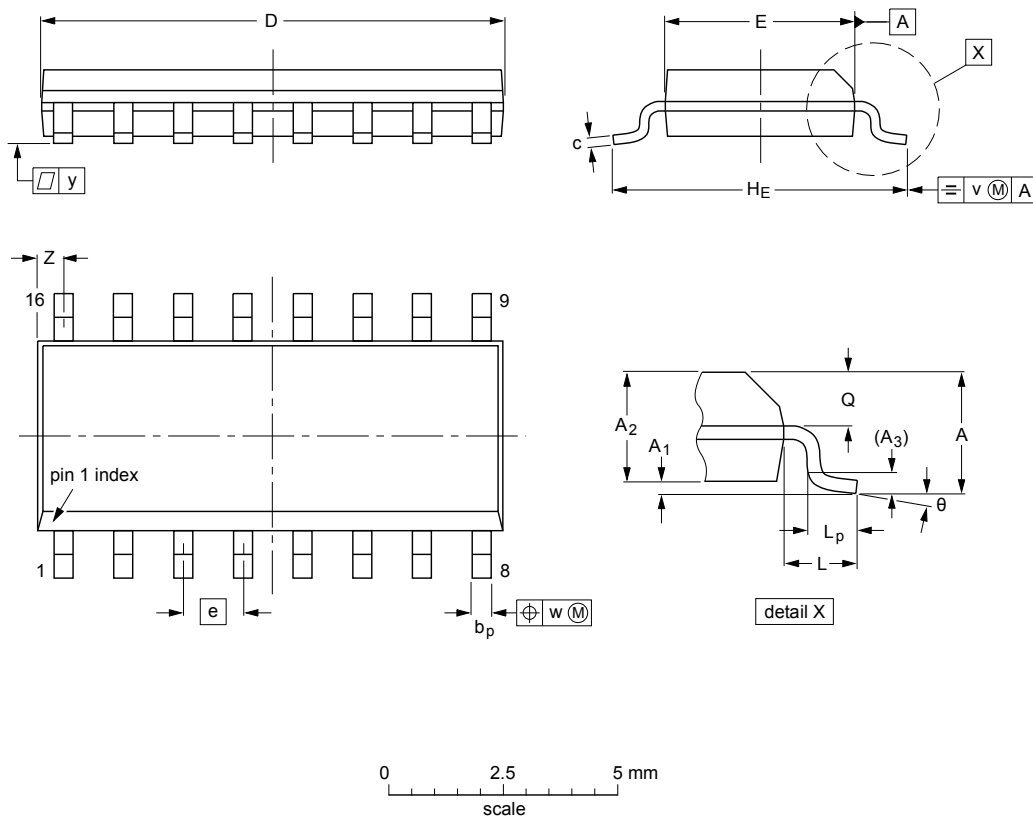
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.8	-	9.9	10	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	1.75	1.75	mm
A ₂	package height	1.25	-	1.35	1.45	mm
e	nominal pitch	-	-	1.27	-	mm
n ₂	actual quantity of termination	-	-	16	-	



2. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

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DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				99-12-27 03-02-19

Fig. 1. Package outline SO16 (SOT109-1)

3. Soldering

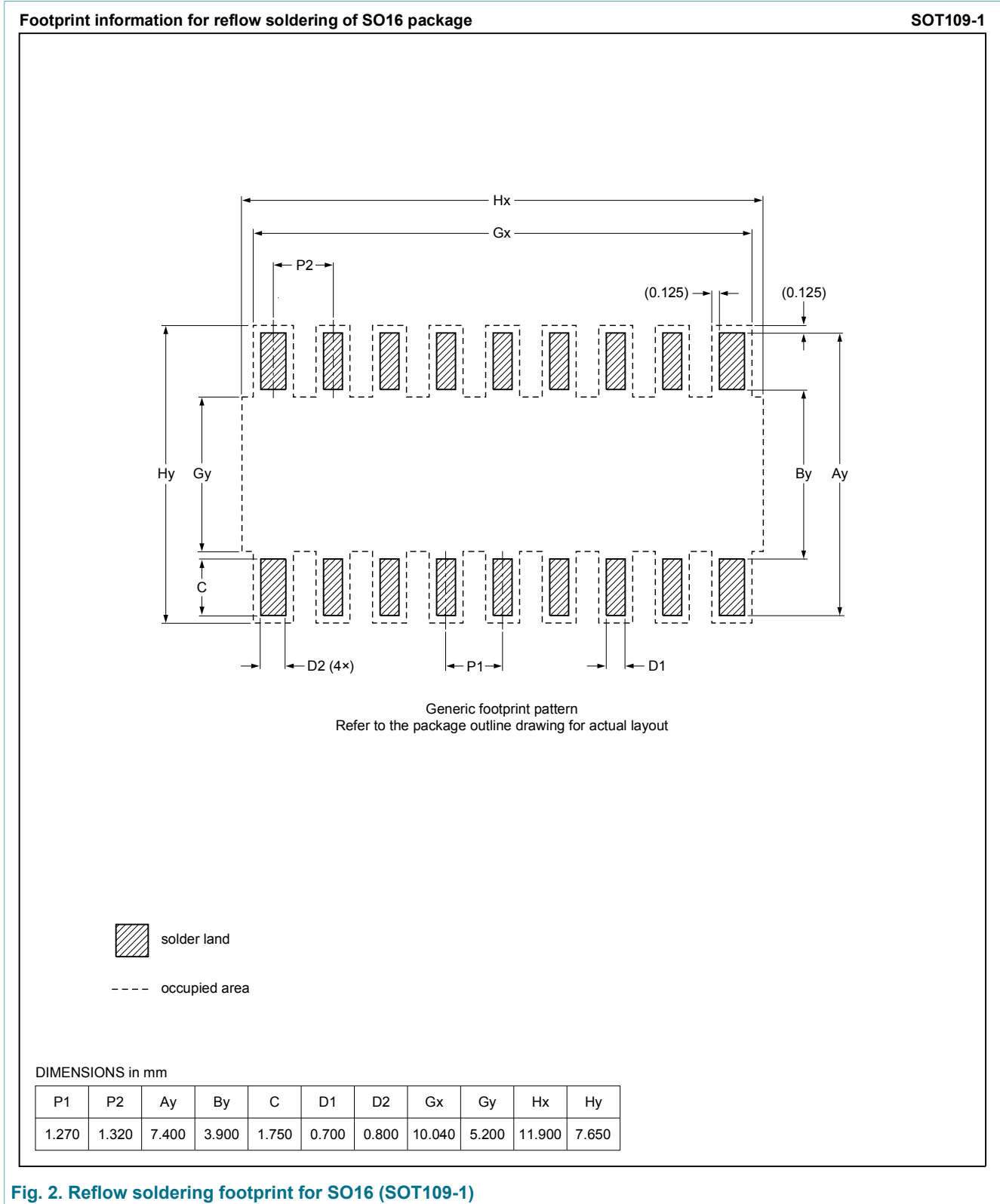


Fig. 2. Reflow soldering footprint for SO16 (SOT109-1)

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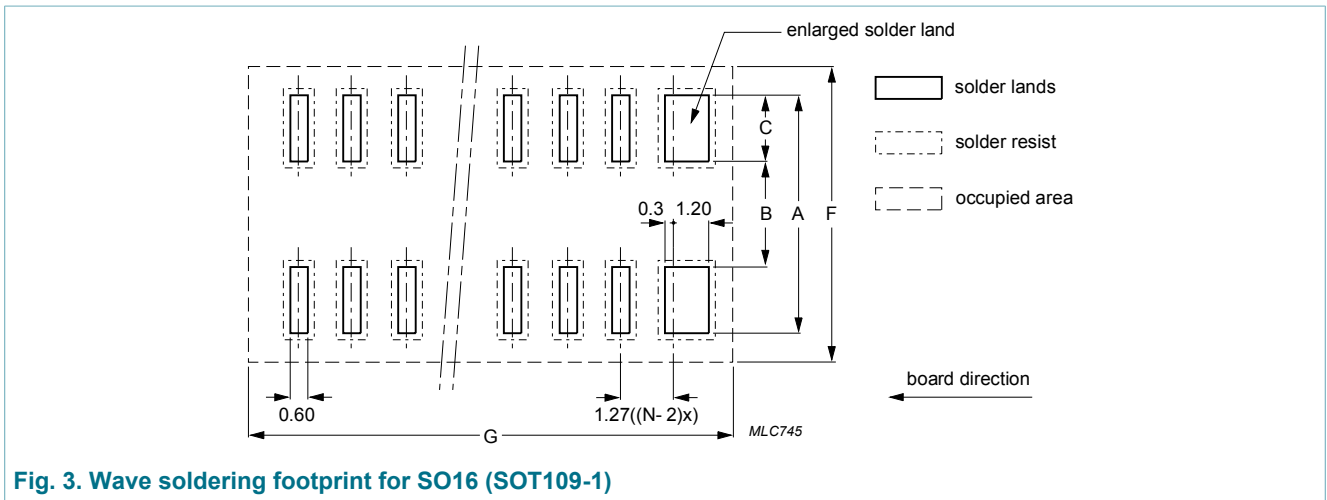


Fig. 3. Wave soldering footprint for SO16 (SOT109-1)

4. Legal information

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